imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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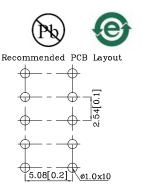


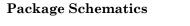
Part Number: XDUG06A

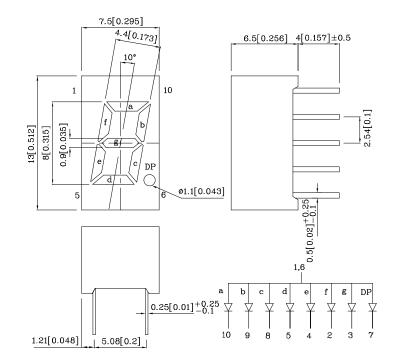
8mm (0.32") SINGLE DIGIT NUMERIC DISPLAY

Features

- \bullet Low power consumption
- \bullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant







Notes: 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit	
Reverse Voltage	V_{R}	V _R 5		
Forward Current	$I_{\rm F}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	$T_{\rm A}$	$\text{-}40 \sim \text{+}85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$	-0	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

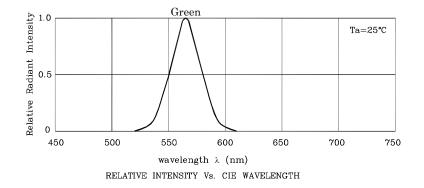
Dperating Characteristics T _A =25°C)		Green (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	$V_{\rm F}$	2	V
Forward Voltage (Max.) (I _F =10mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (V_R =5V)	I_{R}	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle\lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd	Wavelength CIE127-2007* nm λΡ	Description
			min. typ.		
XDUG06A	Green	GaP	360070901400*2490*	565*	Common Anode, Rt.Hand Decimal.

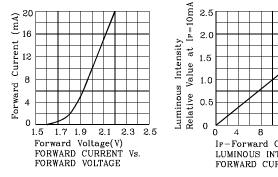
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Oct 17.2016

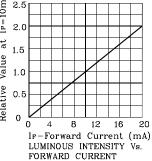
XDSA0131 V10-X Layout: Maggie L.

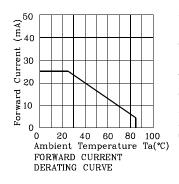


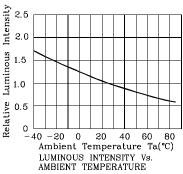


Green

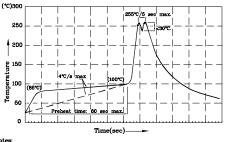








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



mmend pre-heat temperature of 105°C or less (as measured with a noccupie attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 260°C vave soldering temperature between 245°C \sim 255°C for 3 sec (5 se Notes:
1.Recommend pre-heat temperature of 105°C or less (as measured w thermocouple attached to the LED pins) prior to immersion in the wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec max).
3.Do not apply stress to the epoxy resin while the temperature is al 4.Pixtures should not incur stress on the component when mounting during soldering process.
5.SAC 305 colder alloy is recommended.
6.No more than one wave soldering pass.
7.During wave soldering, the PCB top-surface temperature should be kept below 105°C. sec (5 sec

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

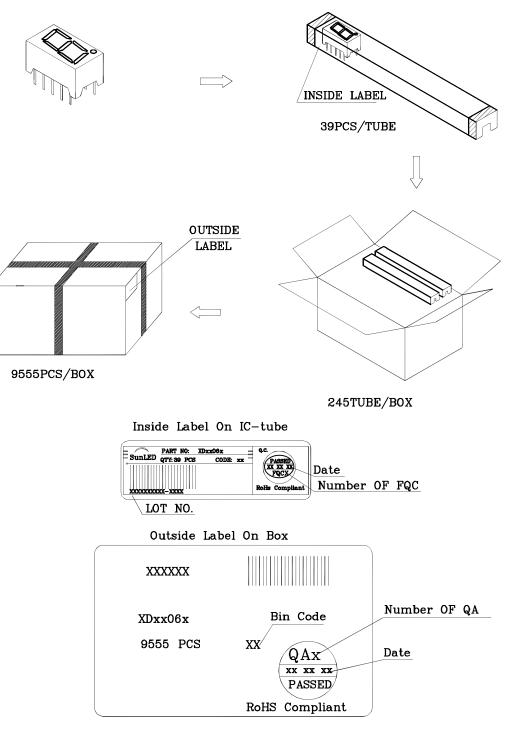
Note: Accuracy may depend on the sorting parameters.

Oct 17,2016



8mm (0.32") SINGLE DIGIT NUMERIC DISPLAY

PACKING & LABEL SPECIFICATIONS



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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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